Si5468DC-T1-GE3-VB Datasheet
N-Channel 30-V (D-S) MOSFET

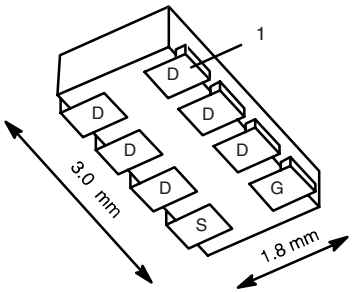
PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
30	0.029 at V_{GS} = 10 V	6.7
	0.035 at V_{GS} = 4.5 V	6.1

FEATURES

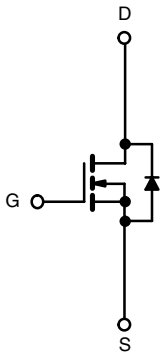
- **Halogen-free According to IEC 61249-2-21 Available**
- Trench Power MOSFET

Pb-free
RoHS COMPLIANT
HALOGEN FREE Available

DFN 3x2



Bottom View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted´					
Parameter		**Symbol**	**5 s**	**Steady State**	**Unit**
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current (T_J = 150 °C)[a]	T_A = 25 °C	I_D	6.7	4.9	A
	T_A = 85 °C		4.8	3.5	
Pulsed Drain Current		I_{DM}	20		
Continuous Source Current (Diode Conduction)[a]		I_S	2.1	1.1	
Maximum Power Dissipation[a]	T_A = 25 °C	P_D	2.5	1.3	W
	T_A = 85 °C		1.3	0.7	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature)[b, c]			260		

THERMAL RESISTANCE RATINGS					
Parameter		**Symbol**	**Typical**	**Maximum**	**Unit**
Maximum Junction-to-Ambient[a]	t ≤ 5 s	R_{thJA}	45	50	°C/W
	Steady State		80	95	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	18	22	

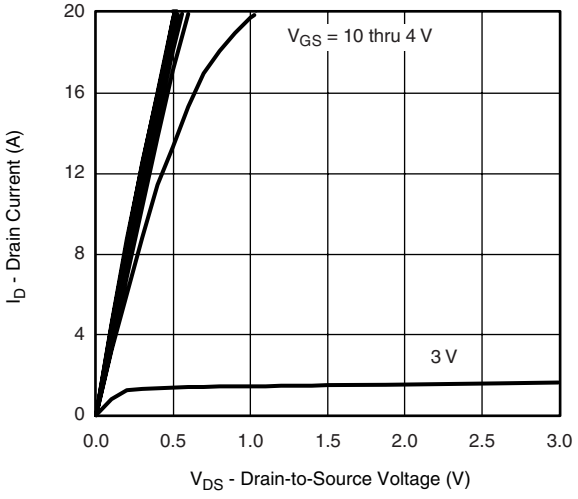
Notes:
a. Surface Mounted on 1" x 1" FR4 board.
b. See Reliability Manual for profile. The DFN3X2 is a leadless package. The end of t he lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

SPECIFICATIONS						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250$ µA	1.0		3.0	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0$ V, $V_{GS} = \pm 20$ V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30$ V, $V_{GS} = 0$ V			1	µA
		$V_{DS} = 30$ V, $V_{GS} = 0$ V, $T_J = 85$ °C			5	
On-State Drain Current[a]	$I_{D(on)}$	$V_{DS} \geq 5$ V, $V_{GS} = 10$ V	20			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 4.9$ A		0.029		Ω
		$V_{GS} = 4.5$ V, $I_D = 4.4$ A		0.035		
Forward Transconductance[a]	g_{fs}	$V_{DS} = 10$ V, $I_D = 4.9$ A		19		S
Diode Forward Voltage[a]	V_{SD}	$I_S = 1.1$ A, $V_{GS} = 0$ V		0.8	1.2	V
Dynamic[b]						
Total Gate Charge	Q_g	$V_{DS} = 15$ V, $V_{GS} = 10$ V, $I_D = 4.9$ A		10	20	nC
Gate-Source Charge	Q_{gs}			1.9		
Gate-Drain Charge	Q_{gd}			1.6		
Gate Resistance	R_g	f = 1 MHz		14		Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15$ V, $R_L = 15$ Ω $I_D \cong 1$ A, $V_{GEN} = 10$ V, $R_g = 6$ Ω		10	15	ns
Rise Time	t_r			10	15	
Turn-Off Delay Time	$t_{d(off)}$			27	40	
Fall Time	t_f			10	15	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 1.1$ A, dI/dt = 100 A/µs		20	60	

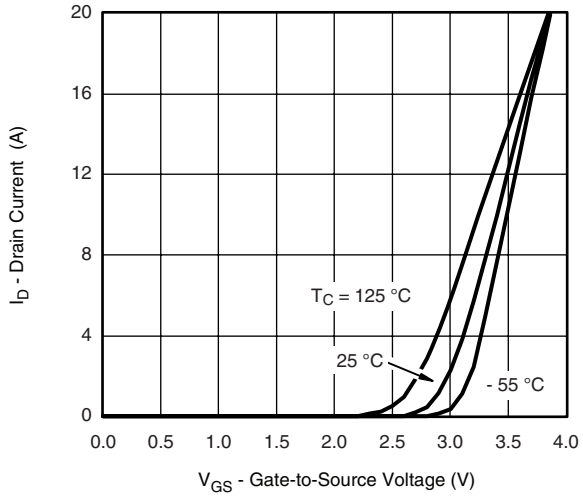
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS T_J = 25 °C, unless otherwise noted

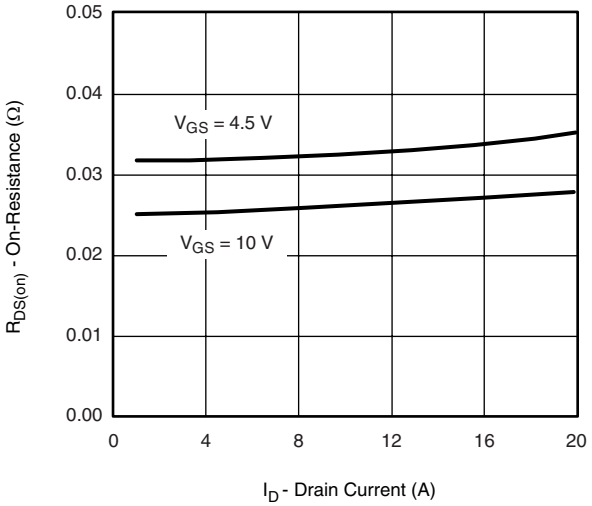


Output Characteristics

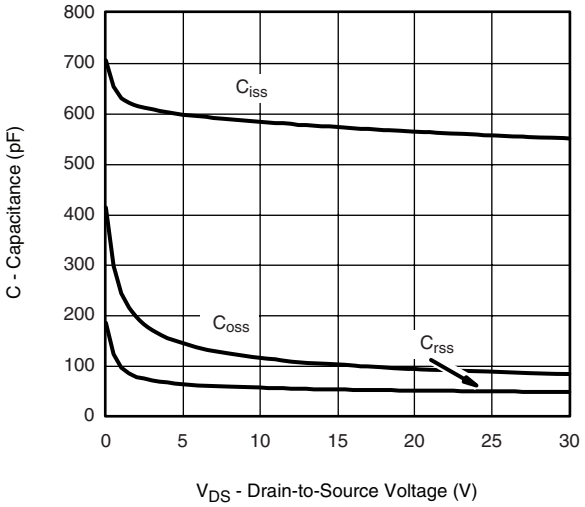


Transfer Characteristics

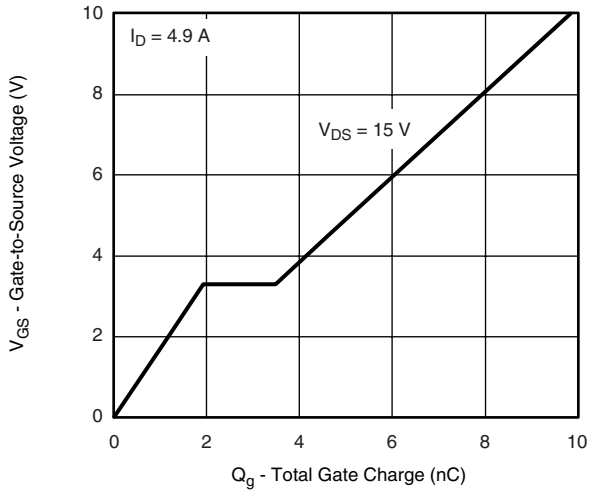
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



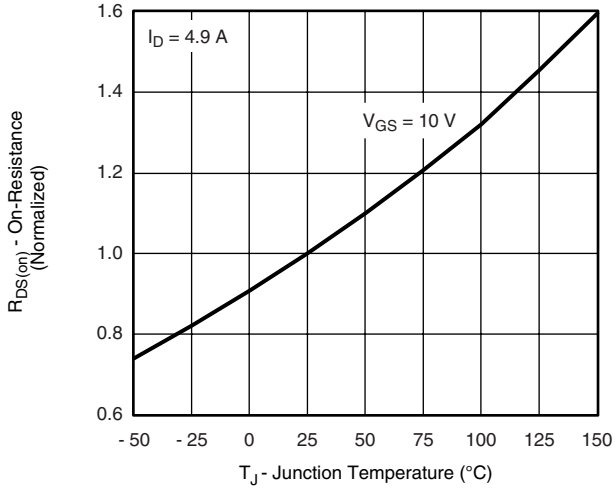
On-Resistance vs. Drain Current



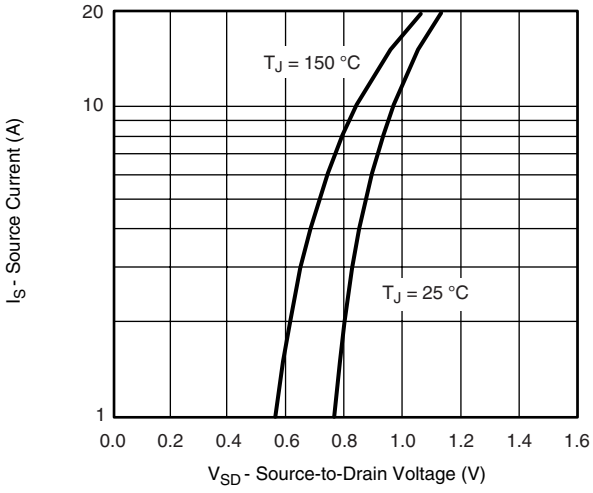
Capacitance



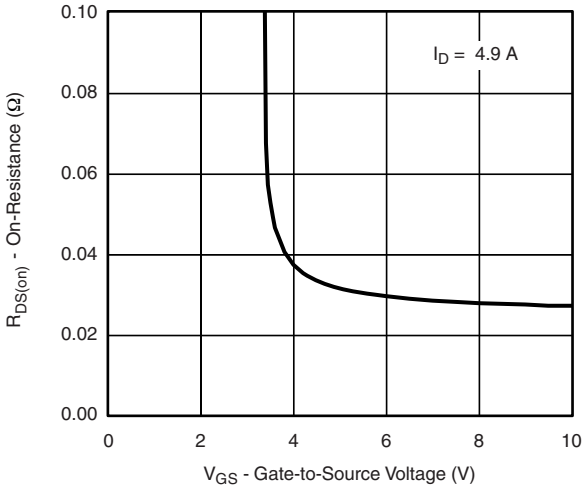
Gate Charge



On-Resistance vs. Junction Temperature

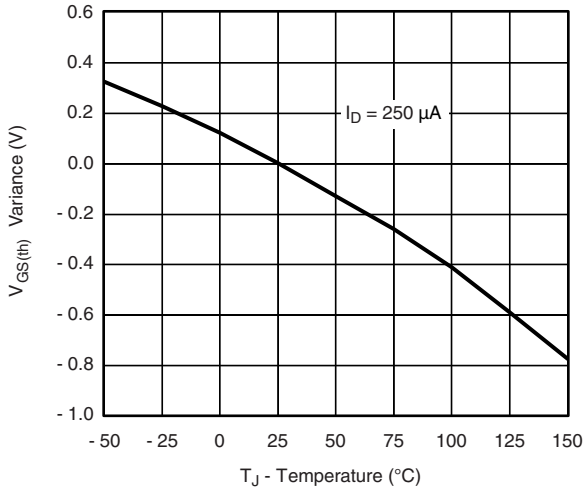


Source-Drain Diode Forward Voltage

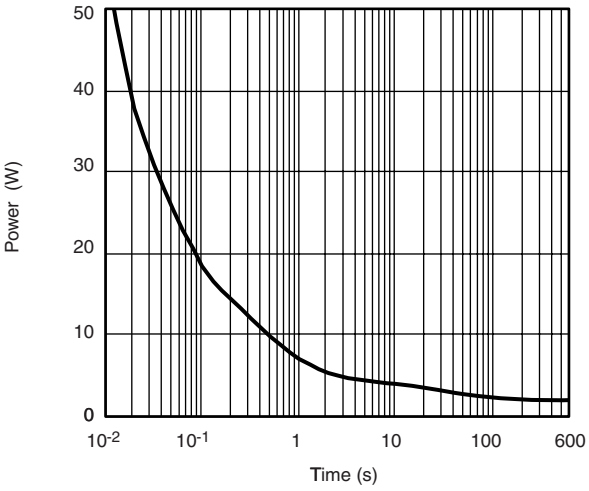


On-Resistance vs. Gate-to-Source Voltage

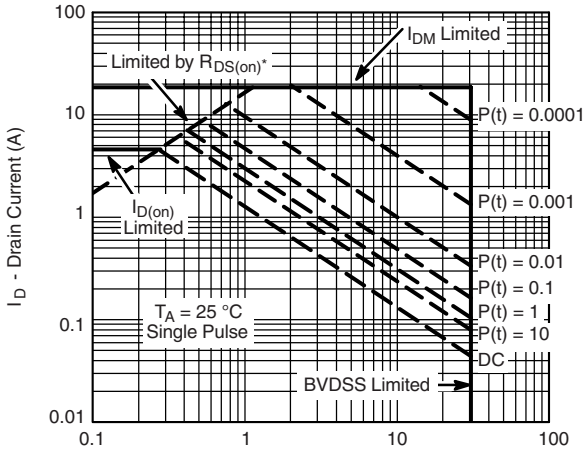
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



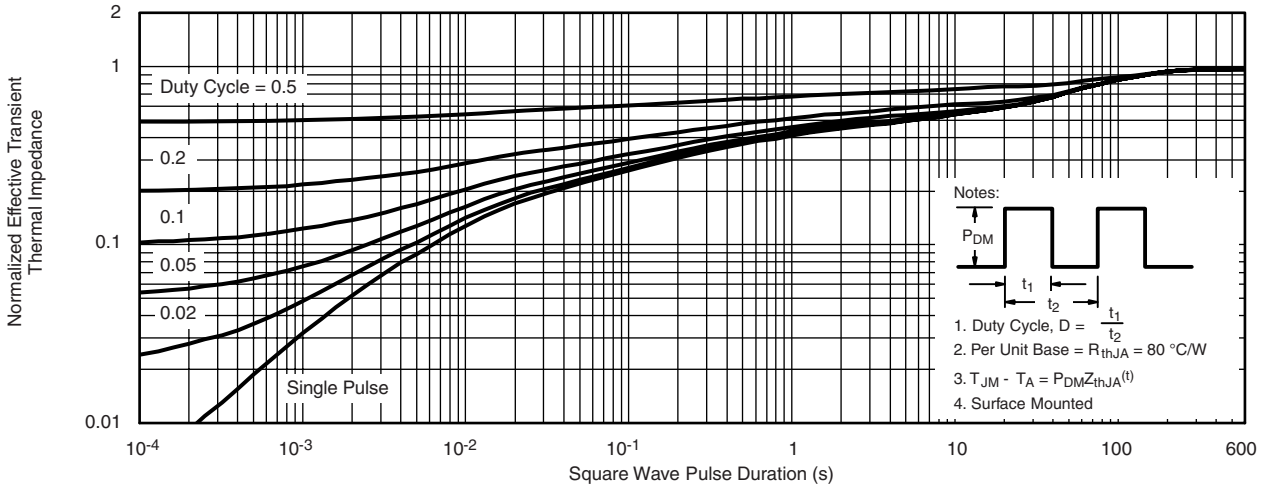
Threshold Voltage



Single Pulse Power

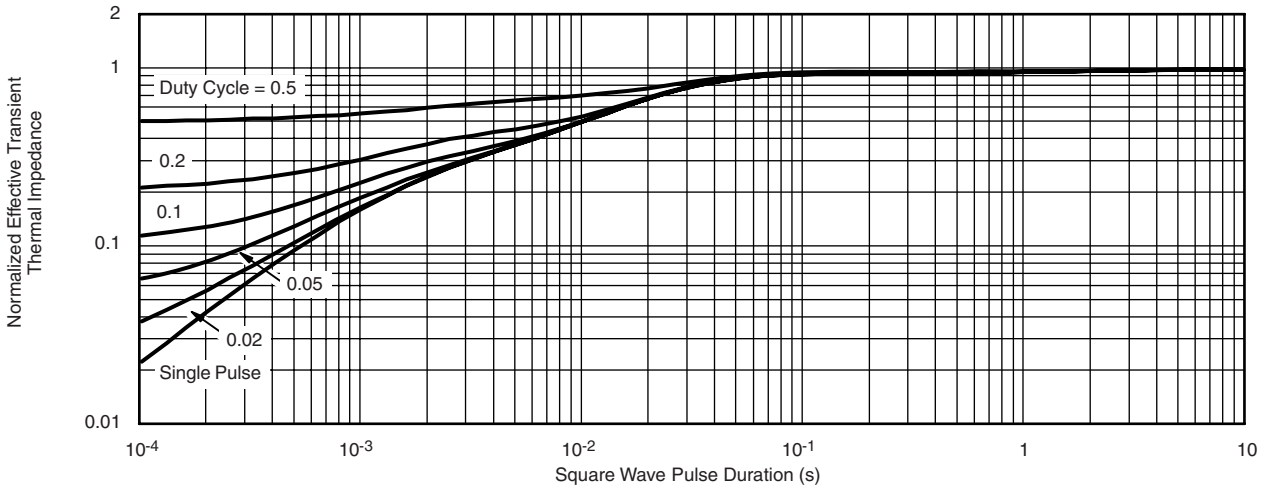


Safe Operating Area



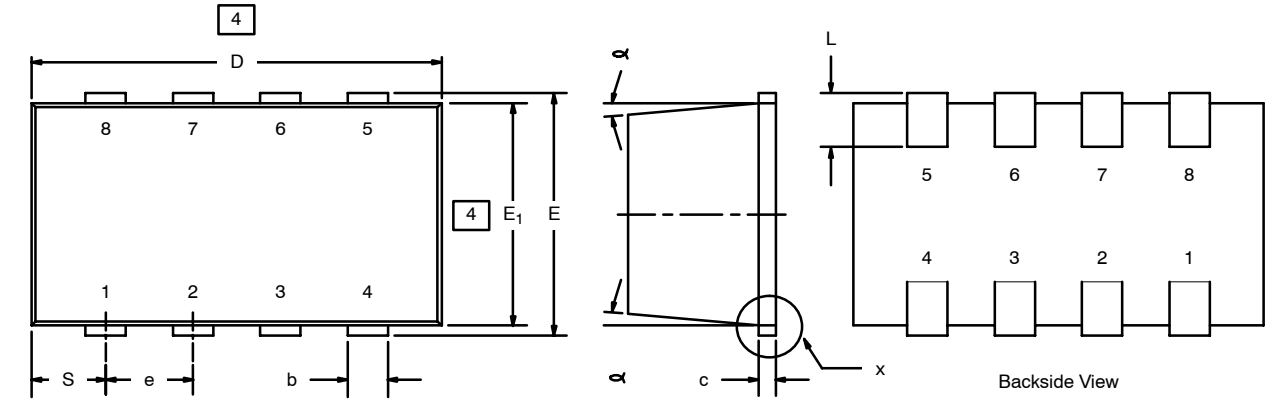
Normalized Thermal Transient Impedance, Junction-to-Ambient

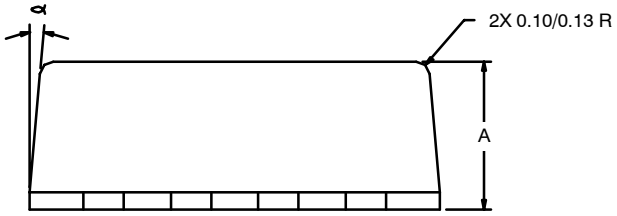
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

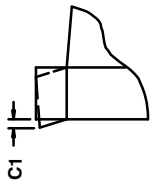


Normalized Thermal Transient Impedance, Junction-to-Foot

DFN 3x2







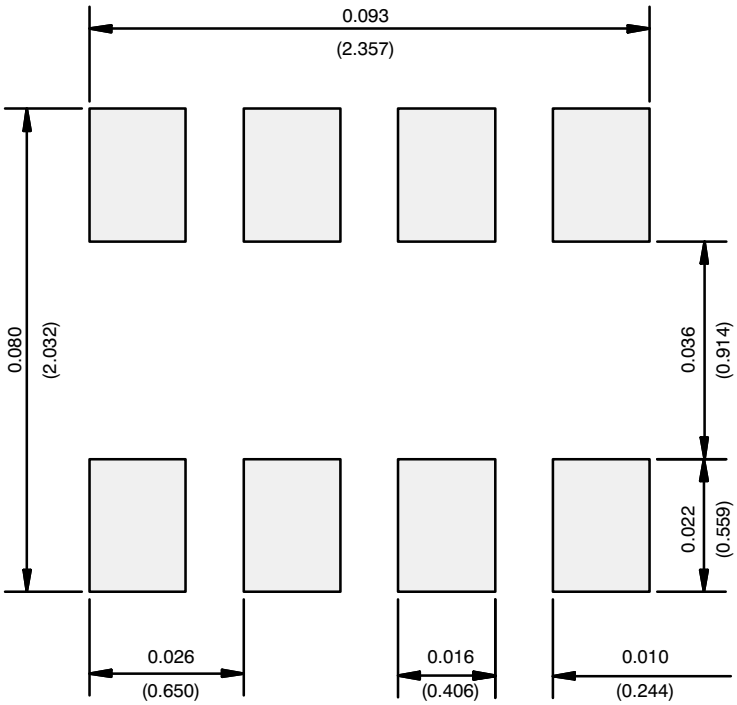
DETAIL X

NOTES:

1. All dimensions are in millimeaters.
2. Mold gate burrs shall not exceed 0.13 mm per side.
3. Leadframe to molded body offset is horizontal and vertical shall not exceed 0.08 mm.
4. Dimensions exclusive of mold gate burrs.
5. No mold flash allowed on the top and bottom lead surface.

Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	1.00	–	1.10	0.039	–	0.043
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.1	0.15	0.20	0.004	0.006	0.008
c1	0	–	0.038	0	–	0.0015
D	2.95	3.05	3.10	0.116	0.120	0.122
E	1.825	1.90	1.975	0.072	0.075	0.078
E_1	1.55	1.65	1.70	0.061	0.065	0.067
e	0.65 BSC			0.0256 BSC		
L	0.28	–	0.42	0.011	–	0.017
S	0.55 BSC			0.022 BSC		
α	5°Nom			5°Nom		
ECN: C-03528—Rev. F, 19-Jan-04 DWG: 5547						

RECOMMENDED MINIMUM PADS FOR DFN3x2



Recommended Minimum Pads
Dimensions in Inches/(mm)

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